

## **MOSFET Maximum Ratings** $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units	
V <sub>DSS</sub>	Drain to Source Voltage	-20	V	
V <sub>GS</sub>	Gate to Source Voltage	±8	V	
	Drain Current Continuous (V <sub>GS</sub> = 4.5V)	-4	^	
D	Pulsed	-20	Α	
E <sub>AS</sub>	Single Pulse Avalanche Energy	72	mJ	
P <sub>D</sub>	Power Dissipation	1.2	W	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to +150	°C	

## **Thermal Characteristics**

$R_{ ext{ heta}JC}$	Thermal Resistance Junction to Case	30	°C/W
$R_{\thetaJA}$	Thermal Resistance Junction to Ambient SSOT-6, 1in <sup>2</sup> copper pad area	103	°C/W

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDC642P	FDC642P_F085	SSOT-6	7"	8mm	3000 units

# **Electrical Characteristics** $T_A = 25^{\circ}C$ unless otherwise noted

Symbol Parameter Test Conditions Min Typ Max Units
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## **Off Characteristics**

<b>B</b> <sub>VDSS</sub>	Drain to Source Breakdown Voltage	$I_{D} = -250 \mu A, V_{GS} = 0 V$	-20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -16V,	-	-	-1	μA
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 8V,$	-	-	±100	nA

### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.4	-0.7	-1.5	V
r	$I_{D} = -4A, V_{GS} = -4.5V$	-	52.5	65		
	Drain to Source On Resistance	$I_D = -3.2A, V_{GS} = -2.5V$	-	75.3	100	mΩ
r <sub>DS(on)</sub>		$I_D = -4A, V_{GS} = -4.5V,$ $T_J = 125^{\circ}C$	-	72.7	105	11122
<b>9</b> FS	Forward Transconductance	$I_D = -4A, V_{DD} = -5V$	-	10	-	S

### **Dynamic Characteristics**

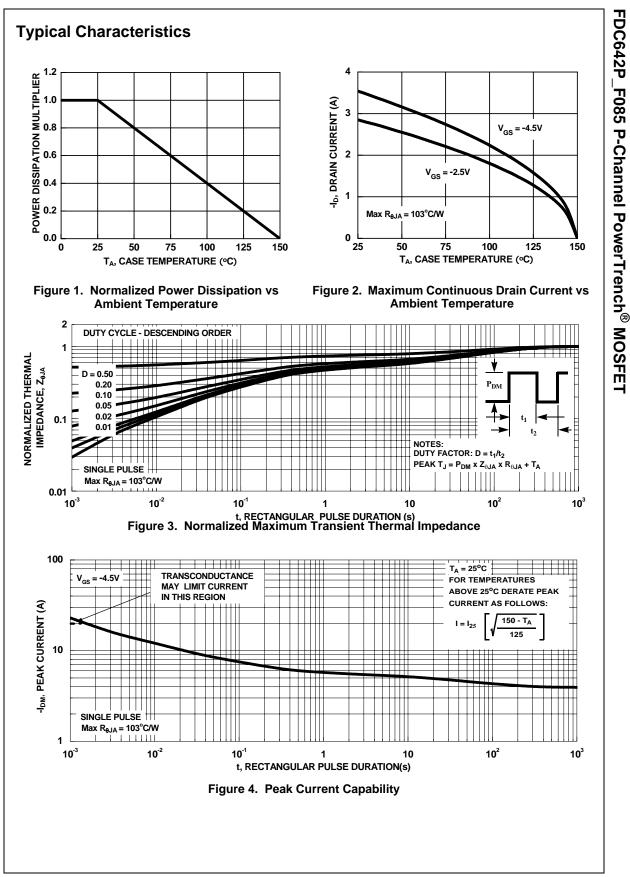
C <sub>iss</sub>	Input Capacitance		-	630	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz	-	160	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	65	-	pF
R <sub>g</sub>	Gate Resistance	f = 1MHz	-	4.4	-	Ω
Q <sub>g(TOT)</sub>	Total Gate Charge at -4.5V		-	6.9	9.0	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>DD</sub> = -10V, I <sub>D</sub> = -4A V <sub>GS</sub> = -4.5V	-	1.2	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	- VGS4.3 V	-	1.8	-	nC

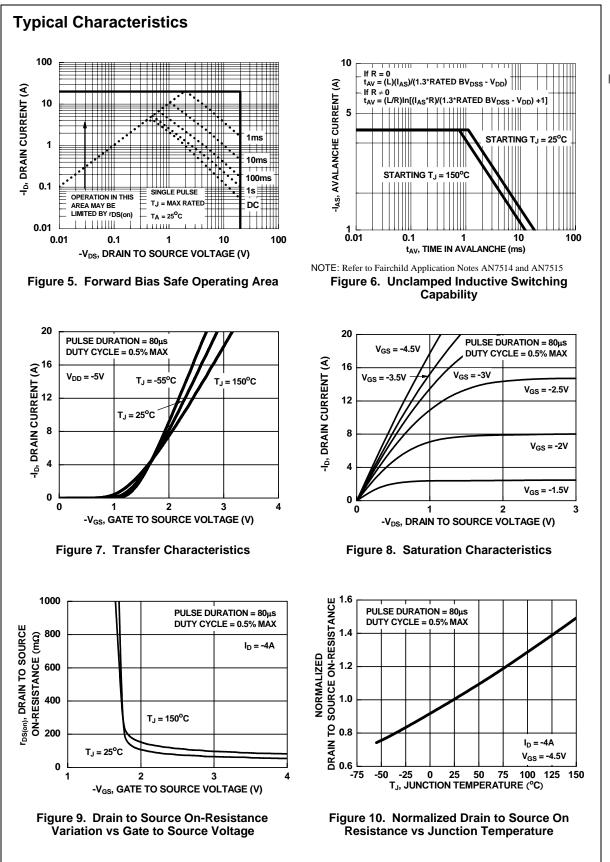
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switch	ing Characteristics					
t <sub>on</sub>	Turn-On Time		-	-	23	ns
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ = -10V, I <sub>D</sub> = -1A $V_{GS}$ = -4.5V, R <sub>GEN</sub> = 6Ω	-	7.3	-	ns
t <sub>r</sub>	Rise Time		-	5.5	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	23.2	-	ns
t <sub>f</sub>	Fall Time		-	9.6	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	53	ns
Drain-So	Source Diode Characteristics	I <sub>SD</sub> = -1.3A	-	-0.7	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = -1.3A, d <sub>SD</sub> /dt = 100A/μs	-	17	22	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$\mu_{\rm F} = 1.5 \Lambda, \alpha_{\rm SD}/\alpha_{\rm f} = 100 \Lambda/\mu_{\rm S}$	-	5.6	7.3	nC

FDC642P\_F085 P-Channel PowerTrench<sup>®</sup> MOSFET

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FDC642P\_F085 Rev. A



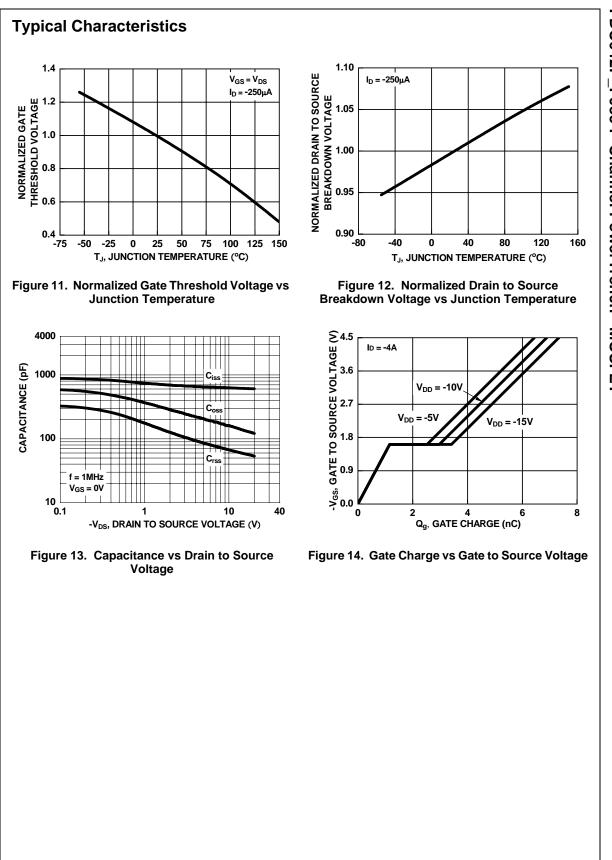


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